



Job Name : TI_DAC38RF80_02262015

Customer : Texas Instruments

Part Num : DAC38RF80

Part Rev : A

Engineer : David Gorden



Layer	Calc Thickness	Primary Stack	Description	Dk / Df
Layer - 1	0.0005 0.0020		Taiyo 4000-BN 1/2oz Sig (Std Plt)	4.71 / 0.0330
Layer - 2	0.0080 0.0006		R-5775K 1/2oz P/G	3.70 / 0.0020
Layer - 3	0.0047 0.0006		R-1650V 1/2oz P/G	3.95 / 0.0153
Layer - 4	0.0040 0.0006		R-1755V 1/2oz Sig	4.50 / 0.0153
Layer - 5	0.0055 0.0006		R-1650V 1/2oz Sig	3.99 / 0.0153
Layer - 6	0.0040 0.0006		R-1755V 1/2oz Mix	4.50 / 0.0153
Layer - 7	0.0046 0.0006		R-1650V 1/2oz P/G	3.95 / 0.0153
Layer - 8	0.0080 0.0020 0.0005		R-1755V 1/2oz Sig (Std Plt) Taiyo 4000-BN	4.50 / 0.0153 4.71 / 0.0330

Materials: Panasonic R-1650V Multifunctional Epoxy Resin (cores R-1755V)
 Panasonic R-1755V Multifunctional Epoxy Resin (prepregs R-1650V)
 Panasonic R-5775K Megtron 6

Requirement	Req. Thickness	Tol +	Tol -	Calc Thick
Incl. Plating & Mask	0.0470	0.0047	0.0047	0.0474
Incl. Mask over Laminate	0.0430	0.0043	0.0043	0.0434
Incl. Plating	0.0460	0.0046	0.0046	0.0464
After Lamination	0.0432	0.0022	0.0022	0.0436
Over Laminate	0.0420	0.0042	0.0042	0.0424

Job Comment
High Speed signals on L1 (Meg6)

Impedance Type	Layer	Design	Actual	Pitch	Plane	Target	Tol (ohms)	Predict
1 Surface MS	L1	0.0190	0.0150	-	-	50	5.0	49.60
	-	-	-	-	L2			
2 EC Microstrip	L1	0.0090	0.0084	0.0150	-	100	10.0	99.49
	-	0.0090	0.0084	-	L2			

Impedance Type	Layer	Design	Actual	Pitch	Plane	Target	Tol (ohms)	Predict
3  RB/CPW Microstrip	L1	-	0.0115	0.0175	-	50	5.0	49.49
	-	-	0.0115	-	L2			
Comment: GND/.006/.0115/.006/GND								
4  EC Microstrip	L8	0.0090	0.0075	0.0150	L7	100	10.0	100.02
	-	0.0090	0.0075	-	-			